

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

**Claims 1-19. (canceled).**

**Claim 20. (new):** A wiring forming method comprising:

a first step of supplying a first liquid containing an insulating material on a substrate to form an insulated pattern on the substrate;

a second step of, after the first step, supplying a second liquid containing a conductive material on the substrate to form a first conductive pattern on the same layer that the first insulated pattern has been formed on;

a third step of, after the second step, applying the second liquid on the first conductive pattern to form a second conductive pattern on the first conductive pattern; and

a fourth step of, after the third step, applying the first liquid on the layer that the first insulated pattern and the first conductive pattern have been formed on to form a second insulated pattern on the same layer that the second conductive pattern has been formed on.

**Claim 21. (new):** The wiring forming method according to claim 20, wherein the first insulated pattern and the first conductive pattern are formed so that they come into contact with each other.

**Claim 22. (new):** The wiring forming method according to claim 20, wherein the first liquid and the second liquid are supplied by using an ink jet system.